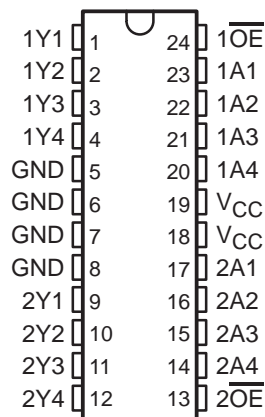


- **EPIC™** (Enhanced-Performance Implanted CMOS) 1-μm Process
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, and Standard Plastic DIPs (NT)

DB, DW, NT, OR PW PACKAGE
(TOP VIEW)

description

The 74AC11244 is an octal buffer or line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as two 4-bit buffers or one 8-bit buffer, with active-low output-enable (\overline{OE}) inputs.

When \overline{OE} is low, the device passes noninverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The 74AC11244 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE
(each driver)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC is a trademark of Texas Instruments Incorporated.

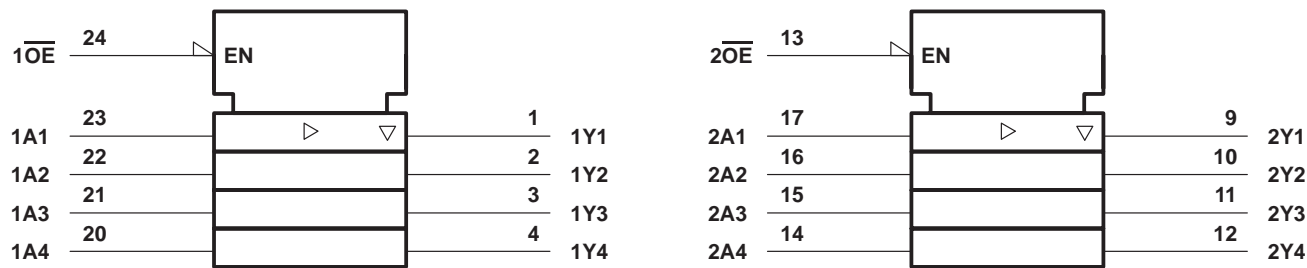
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

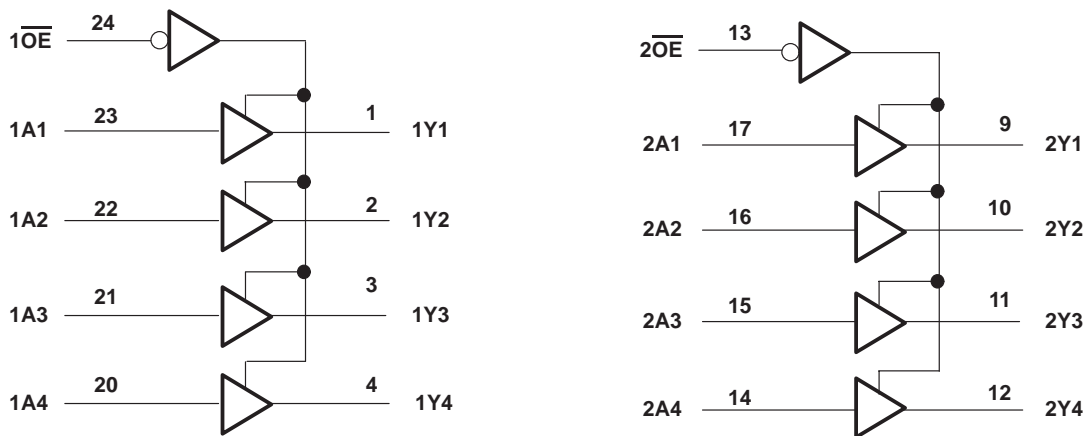
Copyright © 1998, Texas Instruments Incorporated

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±200 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	104°C/W
DW package	81°C/W
PW package	120°C/W
NT package	67°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

74AC11244
OCTAL BUFFER/DRIVER
WITH 3-STATE OUTPUTS

SCAS171B – MARCH 1987 – REVISED SEPTEMBER 1998

[查询"74AC11244DBR"供应商](#)

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	3	5	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1		V
		V _{CC} = 4.5 V	3.15		
		V _{CC} = 5.5 V	3.85		
V _{IL}	Low-level input voltage	V _{CC} = 3 V		0.9	V
		V _{CC} = 4.5 V		1.35	
		V _{CC} = 5.5 V		1.65	
V _I	Input voltage	0		V _{CC}	V
V _O	Output voltage	0		V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V		–4	mA
		V _{CC} = 4.5 V		–24	
		V _{CC} = 5.5 V		–24	
I _{OL}	Low-level output current	V _{CC} = 3 V		12	mA
		V _{CC} = 4.5 V		24	
		V _{CC} = 5.5 V		24	
Δt/Δv	Input transition rise or fall rate	0		10	ns/V
T _A	Operating free-air temperature	–40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V _{OH}	I _{OH} = –50 μA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I _{OH} = –4 mA	3 V	2.58			2.48		
		4.5 V	3.94			3.8		
	I _{OL} = –24 mA	5.5 V	4.94			4.8		
	I _{OH} = –75 mA†	5.5 V				3.85		
V _{OL}	I _{OL} = 50 μA	3 V			0.1		0.1	V
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.44	
		4.5 V			0.36		0.44	
	I _{OL} = 24 mA	5.5 V			0.36		0.44	
	I _{OL} = 75 mA†	5.5 V					1.65	
I _I	V _I = V _{CC} or GND	5.5 V			±0.1		±1	μA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.5		±5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			8		80	μA
C _i	V _I = V _{CC} or GND	5 V		4				pF
C _O	V _O = V _{CC} or GND	5 V		10				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A	Y	1.5	7.1	9.3	1.5	10.2	ns
t _{PHL}			1.5	6.3	8.6	1.5	9.5	
t _{PZH}	$\overline{\text{OE}}$	Y	1.5	8	10.7	1.5	11.8	ns
t _{PZL}			1.5	7.9	10.6	1.5	11.9	
t _{PHZ}	$\overline{\text{OE}}$	Y	1.5	5.9	7.9	1.5	8.3	ns
t _{PLZ}			1.5	7.2	9.4	1.5	9.9	

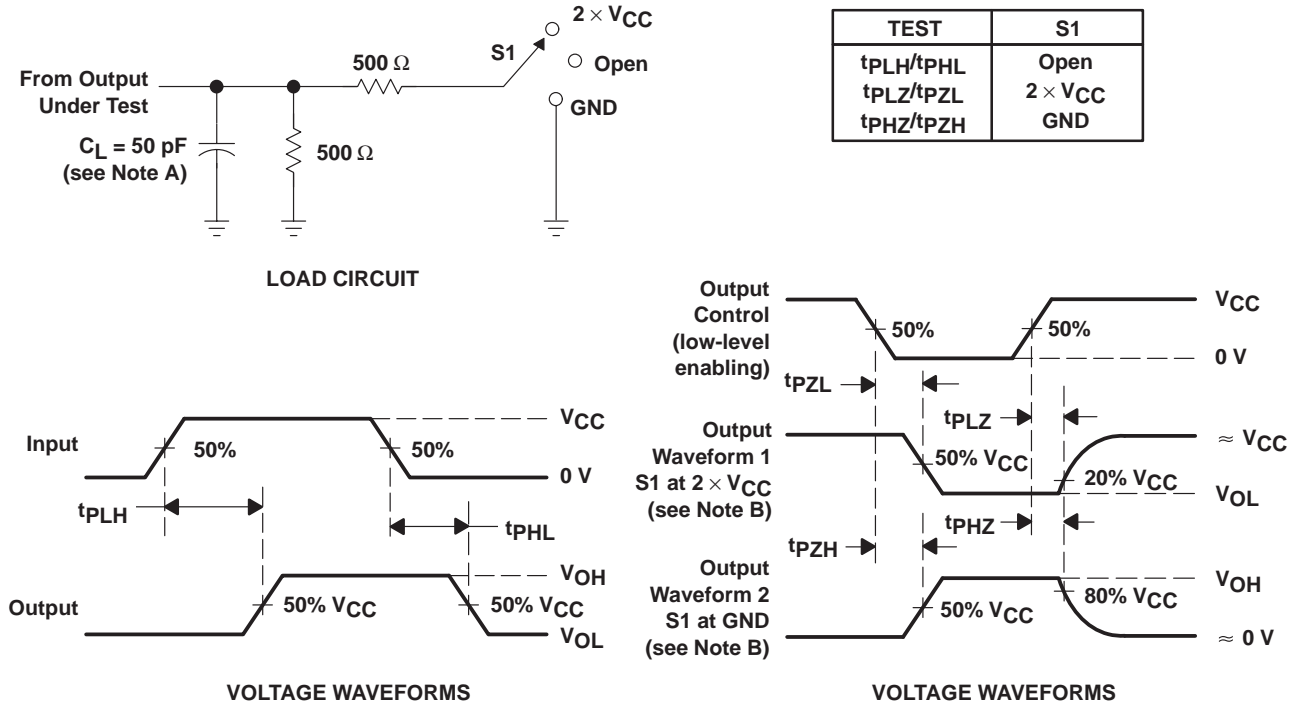
switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A	Y	1.5	4.9	6.7	1.5	7.3	ns
t _{PHL}			1.5	4.5	6.4	1.5	6.9	
t _{PZH}	$\overline{\text{OE}}$	Y	1.5	5.4	7.7	1.5	8.5	ns
t _{PZL}			1.5	5.4	7.6	1.5	8.5	
t _{PHZ}	$\overline{\text{OE}}$	Y	1.5	5.2	7	1.5	7.3	ns
t _{PLZ}			1.5	5.8	7.8	1.5	8.2	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER			TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	Outputs enabled	C _L = 50 pF, f = 1 MHz	27	pF
		Outputs disabled		9	

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
 - D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.